Title: ADaPT Gen III Printed Circuit Board (PCB) Fabrication and Assembly

Statement of work: This procurement request is for the fabrication and assembly of the ADaPT Gen III Antenna PCB's. The design uses specialized microwave PCB substrates along with specific via and trace geometry to ensure proper antenna performance. The attached fabrication and assembly files describe these details for quotation. Upon award additional files will be provided including: BOM, Gerber, NC Drill, ODB and Pick Place. These files are generated by NASA and delivered to the contractor who fabricates and assembles the PCB's according to the design file package.

Salient Specifications: See "ADaPT GEN III PCB, Fabrication Drawing, 20260701.pdf" and "ADaPT GEN III PCB, Assembly Drawing, 20260701.pdf" for board dimensions, stack material, via sizes and counts, conductor geometry tolerances, IPC specification and inspection requirements. The antenna PCB's are made in 2 steps: the fabrication of the PCB itself then the assembly of parts onto the PCB. This request is for 12 PCB's to be fabricated. Then 8 PCB's to have parts assembled with an "Rx' BOM and 4 PCB's assembled with a "Tx" BOM. All 12 PCB's are fabricated with the same exact design. The BOM differences between the "Rx" assembly and "Tx" assembly are drop-in replacements for IC's. This request is for partial consignment where NASA provides long lead commercially available RFIC's (radio frequency integrated circuits).

Lead time: This procurement will need to be invoiced and costed by 9/30/2026. It is preferred to be invoiced with milestone payments if possible. Suggested structure:

- 25% upon completion of engineering review
- 50% upon completion of PCB fabrication
- 25% upon delivery of 12 assembled units